

## Ultra small , Single Band LNA-IC with Band-limiting filter for 600 MHz Band Applications

### FEATURES

- Low voltage operation +2.85 V typ.
- Low current consumption
  - 4 mA typ. (High-Gain mode)
  - 1  $\mu$ A typ. (Low-Gain mode)
- High gain 14.0 dB typ. fRX = 620 MHz (High-Gain mode)
- Low noise figure
  - 1.20 dB typ. fRX = 620 MHz (High-Gain mode)
- Low distortion (IIP3 +10 MHz offset)
  - 4 dBm typ. fRX = 620 MHz (High-Gain mode)
- Small and thin package 6 pin Wafer level chip size package (WLCSP)

### DESCRIPTION

AN26032A is single band LNA-IC for 600 MHz Band applications.

It realizes high performance by using 0.18  $\mu$ m SiGeC Bi-CMOS process ( $f_T$  = 90 GHz,  $f_{max}$  = 140 GHz).

High/Low Gain mode is changeable, controlled by integrated CMOS logic circuit.

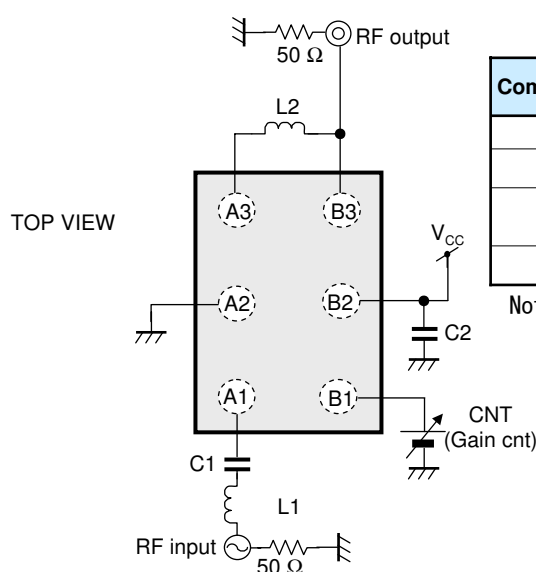
The Band limiting filter is built-in.

A WLCSP package (Wafer Level Chip Sized Package) achieves miniaturization.

### APPLICATIONS

- DTV (UHF)

### SIMPLIFIED APPLICATION



Components	Size	Value	Part Number	Vendor
L1	0603	8.2 nH	LQP03TN8N2H04	Murata
L2	0603	12 nH	LQP03TN12NJ04	Murata
C1	0603	1 000 pF	GRM033B11C102KD01	Murata
C2	0603	100 000 pF	GRM33B30J104KE18	Murata

Notes) This application circuit is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.

## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit	Notes
Supply voltage	$V_{CC}$	3.6	V	*1
Supply current	$I_{CC}$	18	mA	—
Operating ambient temperature	$T_{opr}$	−25 to +85	°C	*2
Operating junction temperature	$T_j$	−40 to +125	°C	*2
Storage temperature	$T_{stg}$	−55 to +125	°C	*2
Input Voltage Range	IN (Pin No.A1)	—	V	*3
	CNT (Pin No.B1)	−0.3 to ( $V_{CC} + 0.3$ )	V	*4
	OUT1 (Pin No.A3)	−0.3 to 1.4	V	—
	OUT2 (Pin No.B3)	−0.3 to 1.4	V	—
ESD	HBM (Human Body Model)	1	kV	—

Notes). This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating.

This rating is the maximum rating and device operating at this range is not guaranteeable as it is higher than our stated recommended operating range.

When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

\*1:The values under the condition not exceeding the above absolute maximum ratings and the power dissipation

\*2:Except for the operating ambient temperature, operating junction temperature, and storage temperature, all ratings are for  $T_a = 25^{\circ}\text{C}$ .

\*3:RF signal input pin. Do not apply DC.

\*4:( $V_{CC} + 0.3$ ) V must not be exceeded 3.6V.

## POWER DISSIPATION RATING

PACKAGE	$\theta_{JA}$	PD ( $T_a=25^{\circ}\text{C}$ )	PD ( $T_a=85^{\circ}\text{C}$ )
WLCSP	1433°C/W	0.070W	0.028W

Note). For the actual usage, please refer to the PD- $T_a$  characteristics diagram in the package specification, supply voltage, load and ambient temperature conditions to ensure that there is enough margin follow the power and the thermal design does not exceed the allowable value.



### CAUTION

Although this has limited built-in ESD protection circuit, but permanent damage may occur on it. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Supply voltage range	$V_{CC}$	2.5	2.85	3.0	V	*1

Note) \*1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

## ELECTRICAL CHARACTERISTICS

Note)  $V_{CC} = 2.85V$

$T_a = 25^{\circ}C \pm 2^{\circ}C$  unless otherwise specified

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
DC electrical characteristics							
Supply current HG	I <sub>ccH</sub>	V <sub>CC</sub> current at High-Gain mode No input signal	—	4.0	5.8	mA	—
Supply current LG	I <sub>ccL</sub>	V <sub>CC</sub> current at Low-Gain mode No input signal	—	1.0	9.5	μA	—
Switching voltage (High-Gain mode)	V <sub>IH</sub>	—	1.40	2.85	—	V	—
Switching voltage (Low-Gain mode)	V <sub>IL</sub>	—	—	0.0	0.55	V	—
Switching current (High)	I <sub>IH</sub>	Current at CNT pin V <sub>IH</sub> = V <sub>CC</sub>	—	4	9.5	μA	—

## ELECTRICAL CHARACTERISTICS (continued)

Note)  $V_{CC} = 2.85 V$

$T_a = 25^{\circ}C \pm 2^{\circ}C$ , f<sub>RX</sub> = 620 MHz, PRX = -30 dBm, CW unless otherwise specified.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
AC electrical characteristics							
Power Gain HG	GHS	High-Gain mode f = fRX	12	14	16	dB	—
Power Gain LG	GLS	Low-Gain mode f = fRX, PRX = −20 dBm	−7	−4.5	−1.5	dB	—
IIP3−10 MHz offset HG	IIP3H1S	High-Gain mode f1 = fRX + 10 MHz f2 = fRX + 20 MHz Input 2 signals (f1, f2)	−4	4	—	dBm	—

# APPLICATION INFORMATION

## REFERENCE VALUES FOR DESIGN

Notes)  $V_{CC} = 2.85\text{ V}$

$T_a = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$ ,  $f_{RX} = 470\text{ MHz}$ ,  $620\text{ MHz}$ ,  $770\text{ MHz}$ ,  $PRX = -30\text{ dBm}$ , CW unless otherwise specified.

Parameter	Symbol	Conditions	Reference values			Unit	Note
			Min	Typ	Max		
AC electrical characteristics							
Power Gain HG	GH	High-Gain mode f = fRX	10.9	14	16.5	dB	*1
Power Gain LG	GL	Low-Gain mode f = fRX, PRX = −20 dBm	−7.5	−4.5	−1.5	dB	*1
Noise Figure HG	NFH	High-Gain mode f = fRX	—	1.3	1.7	dB	*1 ,*2
Noise Figure LG	NFL	Low-Gain mode f = fRX	—	4.5	7.5	dB	*1,*2
IIP3 +10 MHz offset HG	IIP3H1	High-Gain mode f1 = fRX + 10 MHz f2 = fRX + 20 MHz Input 2 signals (f1, f2)	−5	4	—	dBm	*1
IIP3 −10 MHz offset HG	IIP3H2	High-Gain mode f1 = fRX − 10 MHz f2 = fRX − 20 MHz Input 2 signals (f1, f2)	−7	2	—	dBm	*1
Input P1dB HG	IP1dBH	High-Gain mode f = fRX	−14	−10	—	dBm	*1
Reverse Isolation HG	ISOH	High-Gain mode f = fRX	—	−27	—	dB	*1
Reverse Isolation LG	ISOL	High-Gain mode f = fRX	—	−4.5	—	dB	*1
Attenuation1 HG	ATTH1	High-Gain mode f1 = 620 MHz f2 = 1520 MHz Gain(f2) − Gain(f1)	—	−31	−24	dB	*1
Attenuation2 HG	ATTH2	High-Gain mode f1 = 620 MHz f2 = 1880 MHz Gain(f2) − Gain(f1)	—	−49	−41	dB	*1

Note) \*1 : Checked by design, not production tested.

\*2 : Connector & substrate loss (0.1 dB) included.

**APPLICATION INFORMATION (continued)**  
**REFERENCE VALUES FOR DESIGN (continued)**

Notes)  $V_{CC} = 2.5\text{ V to }3.0\text{ V}$

$T_a = -25^{\circ}\text{C to }85^{\circ}\text{C}$  unless otherwise specified.

Parameter	Symbol	Conditions	Reference values			Unit	Note
			Min	Typ	Max		
DC electrical characteristics							
Supply current HG	IccHT	Vcc current at High-Gain mode No input signal	—	4.0	5.9	mA	*1
Supply current LG	IccHT	VCC current at Low-Gain mode No input signal	—	1.0	10	μA	*1
Switching voltage (High Gain Mode)	VIHT	—	1.50	2.85	—	V	*1
Switching voltage (Low Gain Mode)	VILT	—	—	0.0	0.4	V	*1
Switching current (High)	IIHT	Current at CNT pin VIH = Vcc	—	4	10	μA	*1

Note) \*1 : Checked by design, not production tested.

# APPLICATION INFORMATION (continued)

## REFERENCE VALUES FOR DESIGN (continued)

Notes)  $V_{CC} = 2.5 \text{ V to } 3.0 \text{ V}$

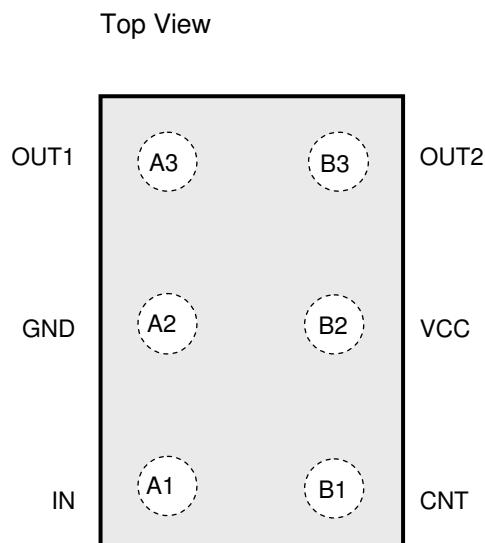
$T_a = -25^\circ\text{C to } 85^\circ\text{C}$ ,  $f_{RX} = 470 \text{ MHz, } 620 \text{ MHz, } 770 \text{ MHz}$ ,  $PRX = -30 \text{ dBm}$ , CW unless otherwise specified.

Parameter	Symbol	Conditions	Reference values			Unit	Note
			Min	Typ	Max		
AC electrical characteristics							
Power Gain HG	GHT	High-Gain mode f = fRX	10.4	14	17	dB	*1
Power Gain LG	GLT	Low-Gain mode f = fRX, PRX = −20 dBm	−8	−4.5	−1.5	dB	*1
Noise Figure HG	NFHT	High-Gain mode f = fRX	—	1.3	2.4	dB	*1 ,*2
Noise Figure LG	NFLT	Low-Gain mode f = fRX	—	4.5	8.0	dB	*1,*2
IIP3 +10 MHz offset  HG	IIP3H1Ta	High-Gain mode f1 = fRX + 10 MHz f2 = fRX + 20 MHz Input 2 signals (f1, f2)	−6	4	—	dBm	*1
IIP3 −10 MHz offset  HG	IIP3H2Ta	High-Gain mode f1 = fRX − 10 MHz f2 = fRX − 20 MHz Input 2 signals (f1, f2)	−8	2	—	dBm	*1
Input P1dB  HG	P1dBHT	High-Gain mode f = fRX	−16	−10	—	dBm	*1
Attenuation1 HG	ATTHT1	High-Gain mode f1 = 620 MHz f2 = 1520 MHz Gain(f2) − Gain(f1)	—	−31	−23	dB	*1
Attenuation2 HG	ATTHT2	High-Gain mode f1 = 620 MHz f2 = 1880 MHz Gain(f2) − Gain(f1)	—	−49	−40	dB	*1

Note) \*1 : Checked by design, not production tested.

\*2 : Connector & substrate loss (0.1 dB) included.

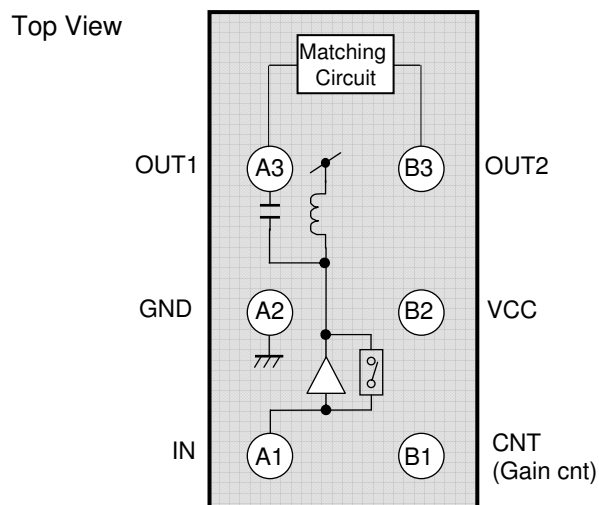
## PIN CONFIGURATION



## PIN FUNCTIONS

Pin No.	Pin name	Type	Description
A1	IN	Input	RF Input
A2	GND	Ground	GND
A3	OUT1	Output	RF Output
B1	CNT	Input	High-Gain / Low-Gain switch L: Low-Gain Mode H: High-Gain Mode
B2	VCC	Power Supply	V <sub>CC</sub>
B3	OUT2	Output	RF output

## FUNCTIONAL BLOCK DIAGRAM

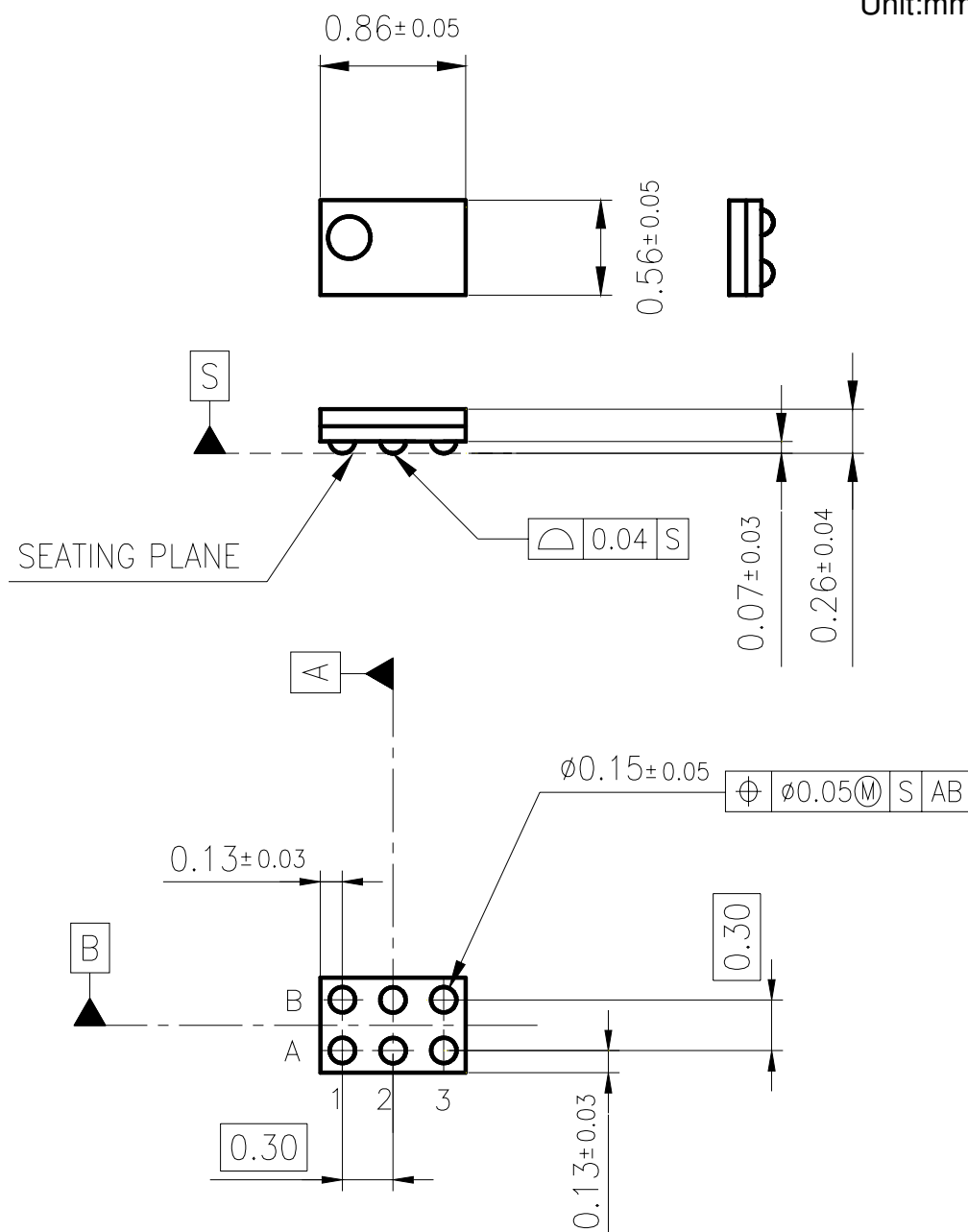


Notes) This circuit and these circuit constants show an example and do not guarantee the design as a mass-production set.  
This block diagram is for explaining functions. The part of the block diagram may be omitted, or it may be simplified.

PACKAGE INFORMATION ( Reference Data )

Package Code:ALGA006-W-0609AQA

Unit:mm



Body Material : Br/Sb Free Epoxy Resin
Reroute Material : Cu
Bump : SnAgCu



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3. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might smoke or ignite.
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5. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
6. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short) .

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